502608471 12/19/2013

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2654891

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
YEN-JEN CHEN	11/29/2011	
I-TING LEE	11/29/2011	
FENG WEI KUO	11/29/2011	
HUAN-NENG CHEN	11/29/2011	
CHEWN-PU JOU	11/29/2011	

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14133982

CORRESPONDENCE DATA

Fax Number:

7036841111 Phone: Email: tsmc@ipfirm.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: LOWE HAUPTMAN & HAM, LLP (TSMC)

2318 MILL ROAD Address Line 1: Address Line 2: **SUITE 1400**

Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER: T5057-635A

PATENT

REEL: 031818 FRAME: 0581

502608471

NAME OF SUBMITTER:	RANDY A. NORANBROCK
Signature:	/Randy A. Noranbrock/
Date:	12/19/2013
Total Attachments: 1 source=efiledassgn#page1.tif	

PATENT REEL: 031818 FRAME: 0582

Docket No. T5057-635

ASSIGNMENT

In consideration of the premises and	other good and	valuable consideration	in hand paid,	the receipt an	d sufficiency of
which is hereby acknowledged, the undersigned	∍d,				, v-

1) Yen-Jen CHEN

4) Huan-Neng CHEN

2) I-Ting LEE

5) Chewn-Pu JOU

3) Feng Wei KUO

who has made a certain new and useful invention, hereby sells, assigns and transfers unto -

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

PHASE FREQUENCY DETECTOR CIRCUIT

- (a) for which an application for United States Letters Patent was filed on $\frac{11/30/2011}{2011}$, and identified by United States Patent Application No. $\frac{13/308,274}{2011}$; or
- (b) for which an application for United States Letters Patent was executed on

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Len Jen Chen
Name: Yen-Jen CHEN

2) I Ting Cee
Name: I-Ting LEE

3) Fend Wei KUO
Name: Feng Wei KUO

4) HUAN-Neng CHEN
Name: Huan-Neng CHEN

5) Ourfor
Name: Chewn-Pu JOU

Date: 2011. 11. 29

Date:

2011, 11, 29 ate:

7011. (1.29 Date:

2011, 11, 29 Date:

> PATENT REEL: 031818 FRAME: 0583

RECORDED: 12/19/2013